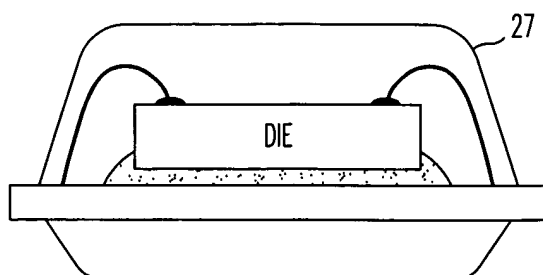
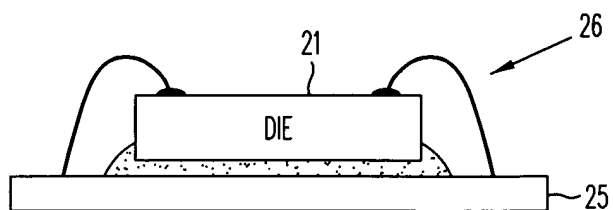
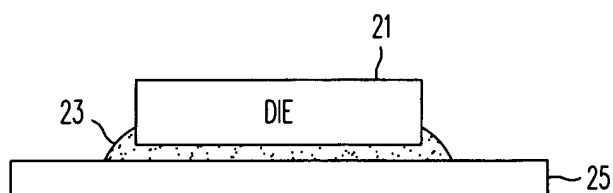
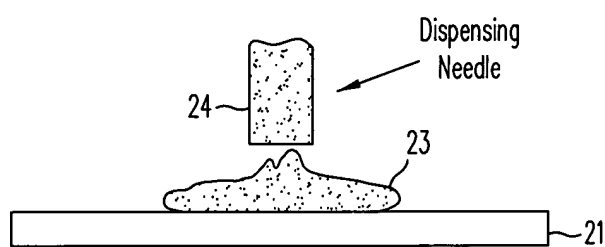
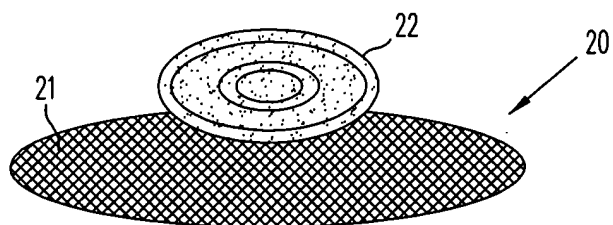


Fig. 1 is a cross-sectional view of a semiconductor device. The device features a central region 102. Within this region, there are components labeled 108a, 108b, 110a, 110b, 112a, and 112b. The device is connected to a power supply Vcc and a ground or power supply Vdd or GND. A current 1A is shown flowing from Vcc and into Vdd or GND. The device is mounted on a substrate 104, which has a pad 112.



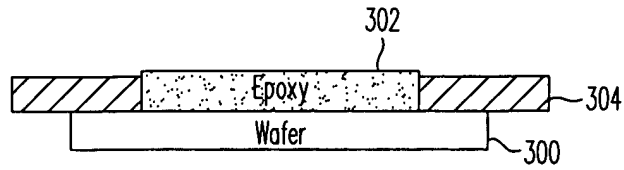


FIG. 3A

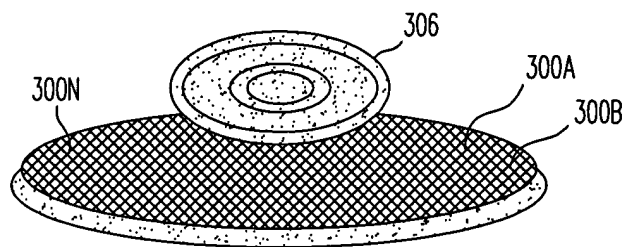


FIG. 3B

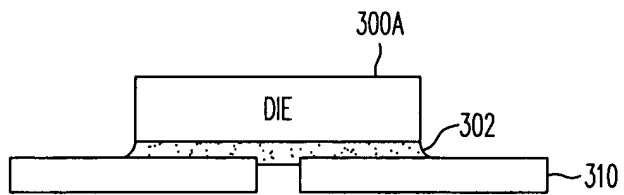


FIG. 3C

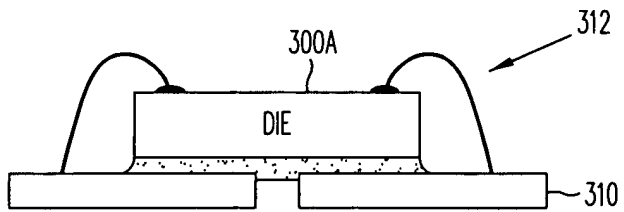


FIG. 3D

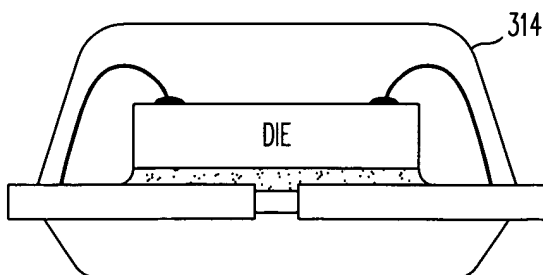


FIG. 3E

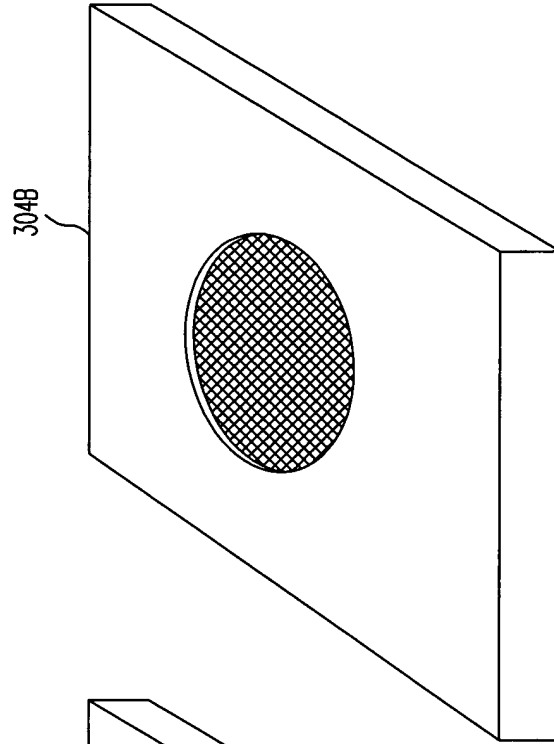


FIG. 4A

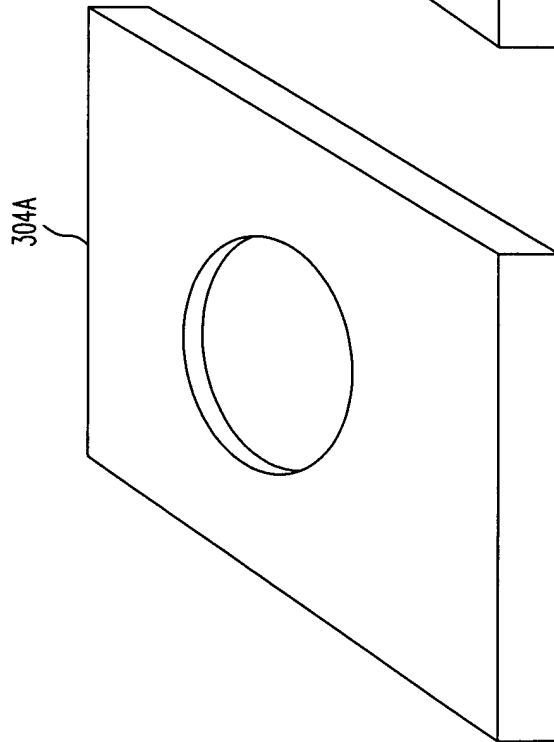


FIG. 4B

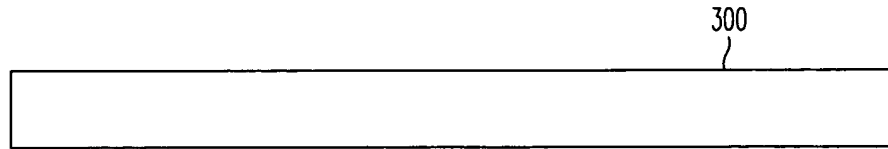


FIG. 5A

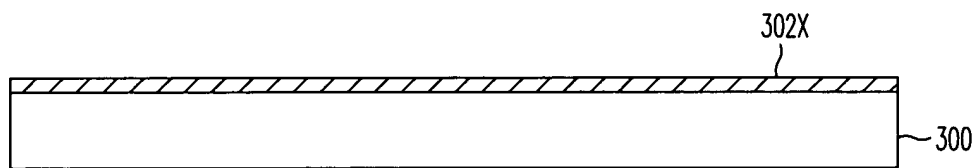


FIG. 5B

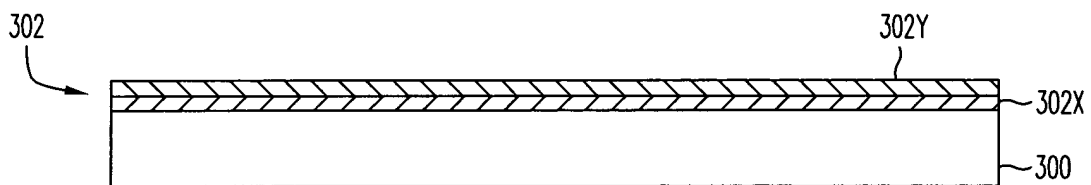


FIG. 5C

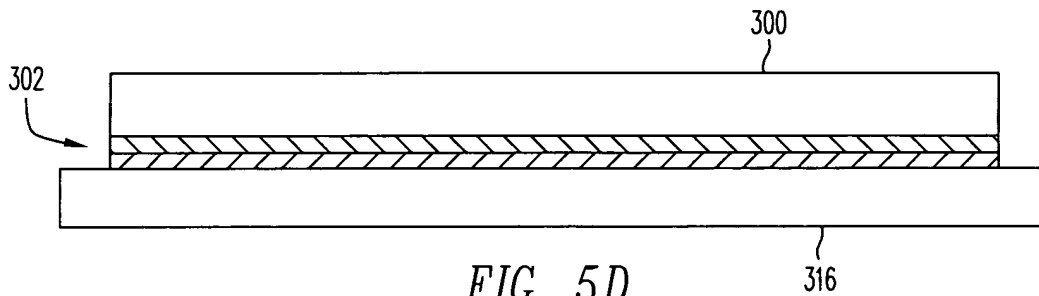


FIG. 5D

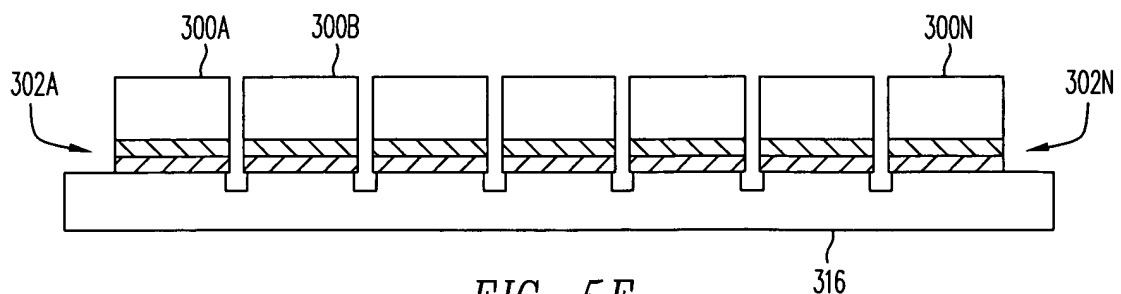


FIG. 5E

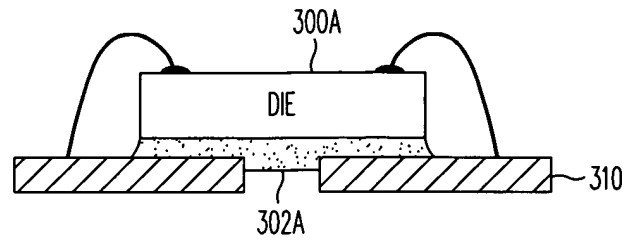


FIG. 6A

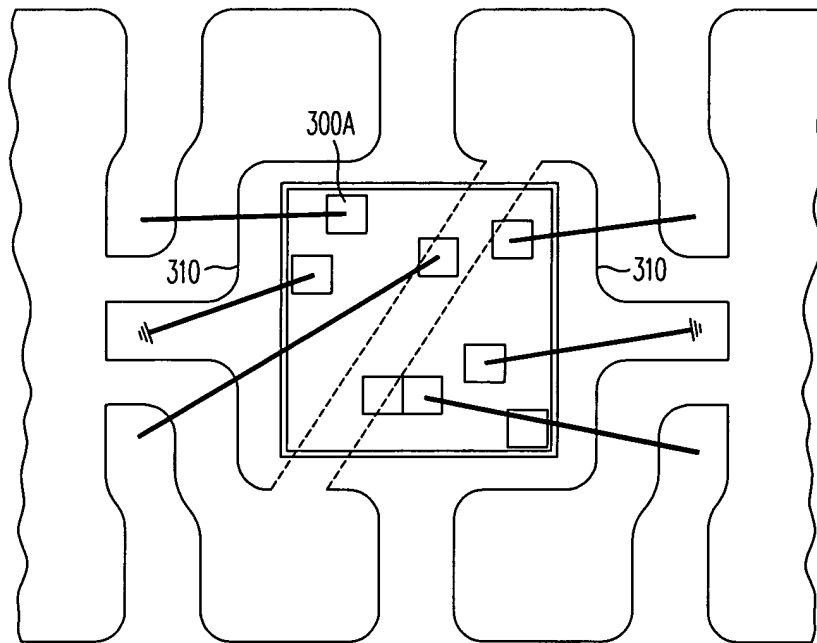


FIG. 6B

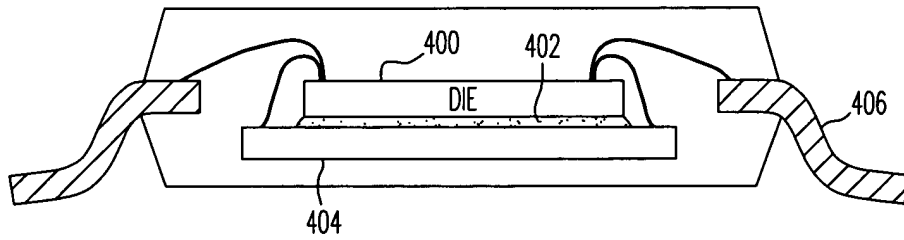


FIG. 7

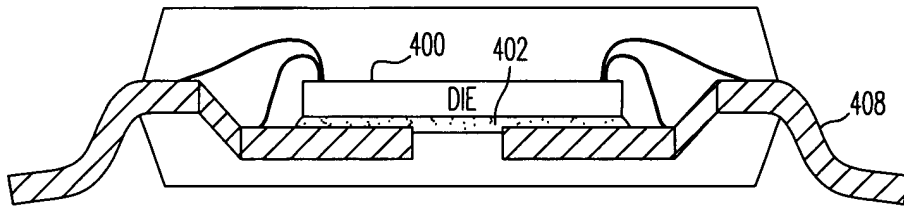


FIG. 8

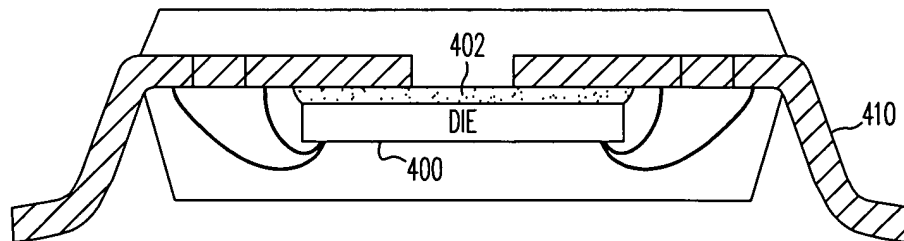


FIG. 9

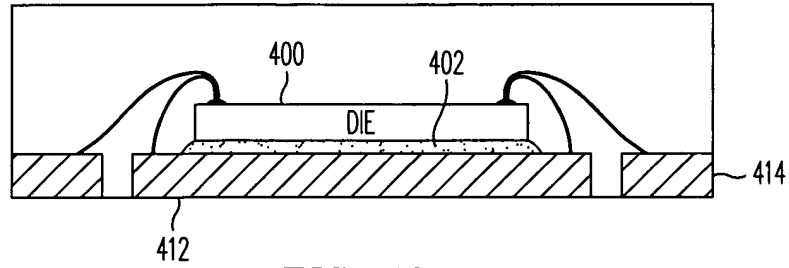


FIG. 10

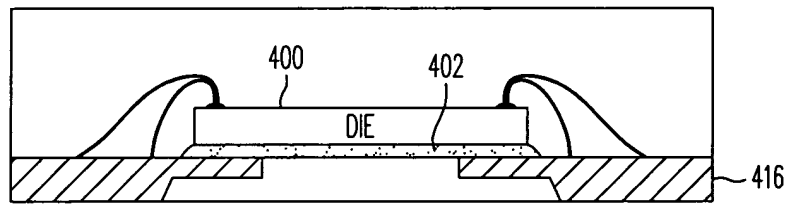


FIG. 11

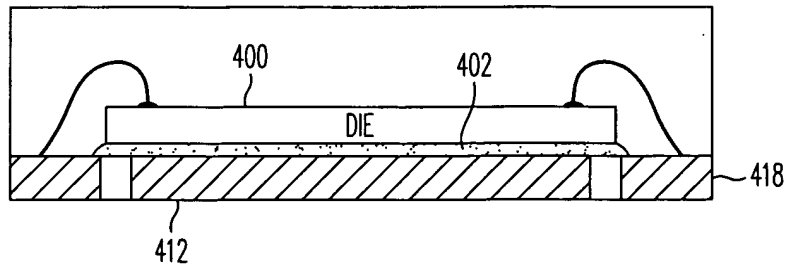


FIG. 12



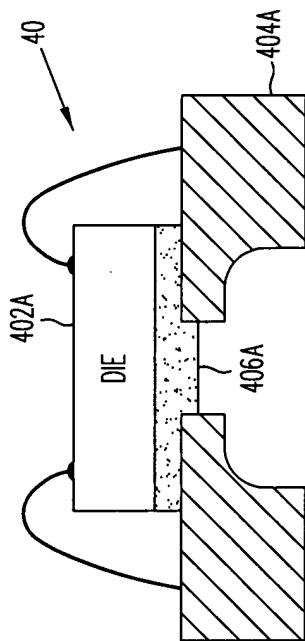


FIG. 13A

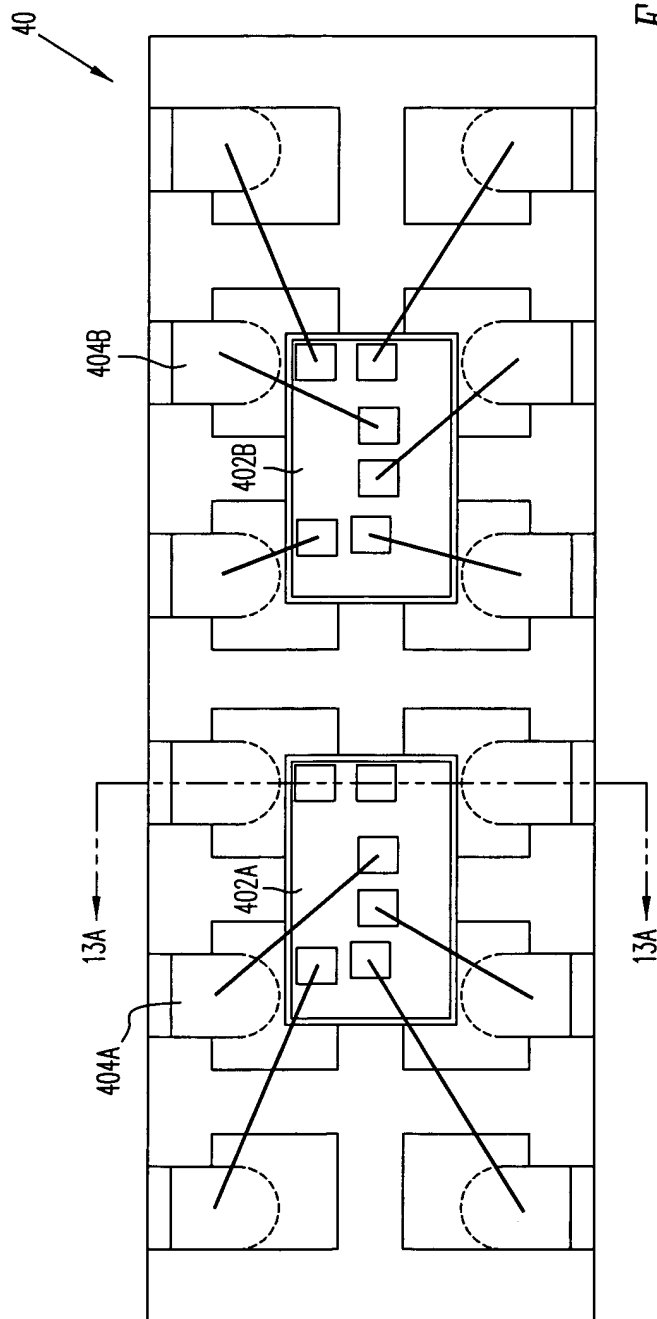


FIG. 13B

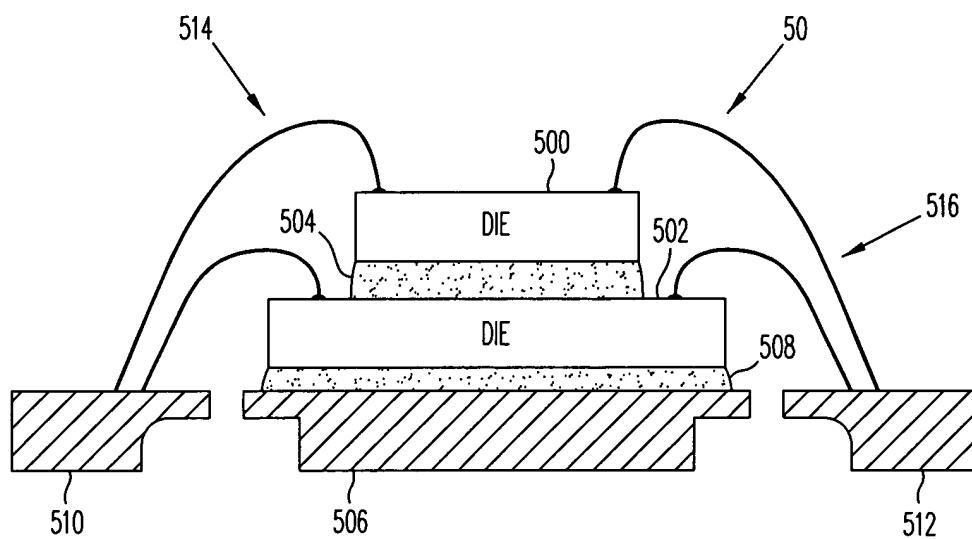


FIG. 14

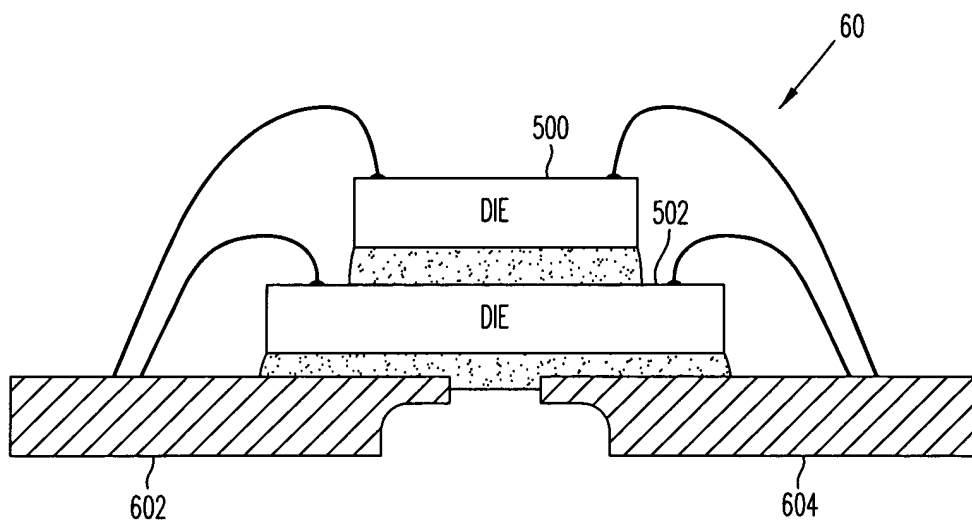


FIG. 15